Surface Mount Fast Recovery Rectifier

Features

- Low profile package
- Ideal for automated placement
- Glass passivated chip junction
- High forward surge capability
- Fast reverse recovery time
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C

Typical Applications

For use in high frequency rectification of power supplies, inverters, converters, and freewheeling diodes for consumer, and telecommunication.

Mechanical Data

- **Package**: SMBF
  Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant, halogen-free
- **Terminals**: Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Polarity:** Cathode line denotes the cathode end

■Maximum Ratings (T_a=25 SYMBOL

		UNIT	GR2ABF	GR2BBF	GR2DBF	GR2GBF	**GR2JBF**	**GR2KBF**	**GR2MBF**
Device marking code			GR2ABF	GR2BBF	GR2DBF	GR2GBF	GR2JBF	GR2KBF	GR2MBF
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	V	50	100	200	400	600	800	1000
Maximum RMS Voltage	V_{RMS}	V	35	70	140	280	420	560	700
Maximum DC blocking Voltage	V_{DC}	V	50	100	200	400	600	800	1000
Average rectified output current @60Hz sine wave, resistance load, TL (Fig.1)	I_O	A	2.0						
Forward Surge Current (Non-repetitive) @60Hz Half-sine wave,1 cycle, Tj=25	I_{FSM}	A	50						
Forward Surge Current (Non-repetitive) @1ms, square wave, 1 cycle, Tj=25			100						
Current squared time @1ms≤t≤8.3ms Tj=25 Rating of per diode	I^2t	A^2s	10.375						
Typical junction capacitance @Measured at 1MHz and Applied Reverse Voltage of 4.0 V.D.C	Cj	pF	18				11		
Storage temperature	T_{stg}		-55 ~ +150						
Junction temperature	T_j		-55 ~ +150						

■Electrical Characteristics T_a=25 Unless otherwise specified

PARAMETER	SYMBOL	UNIT	TEST CONDITIONS	GR2ABF	GR2BBF	GR2DBF	GR2GBF	GR2JBF	GR2KBF	GR2MBF
Maximum instantaneous forward voltage drop per diode	V_F	V	I_{FM}=2.0A	1.3						
Maximum reverse recovery time	t_{rr}	ns	I_F=0.5A,I_R=1.0A, I_{rr}=0.25A	150				250	500	
Maximum DC reverse current at rated DC blocking voltage per diode	I_R	μA	T_j=25	5.0						
			T_j=125	100						

■Thermal Characteristics T_a=25 Unless otherwise specified

PARAMETER	SYMBOL	UNIT	GR2ABF	GR2BBF	GR2DBF	GR2GBF	GR2JBF	GR2KBF	GR2MBF
Typical Thermal Resistance	$R_{\theta J-A}$(1)	/W	60						
	$R_{\theta J-L}$(1)		20						
	$R_{\theta J-C}$(1)		15						

Note:
(1) Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.3" x 0.3" (8.0 mm x 8.0 mm) copper pad areas

■ Characteristics (Typical)

FIG.1: Io-TL Curve

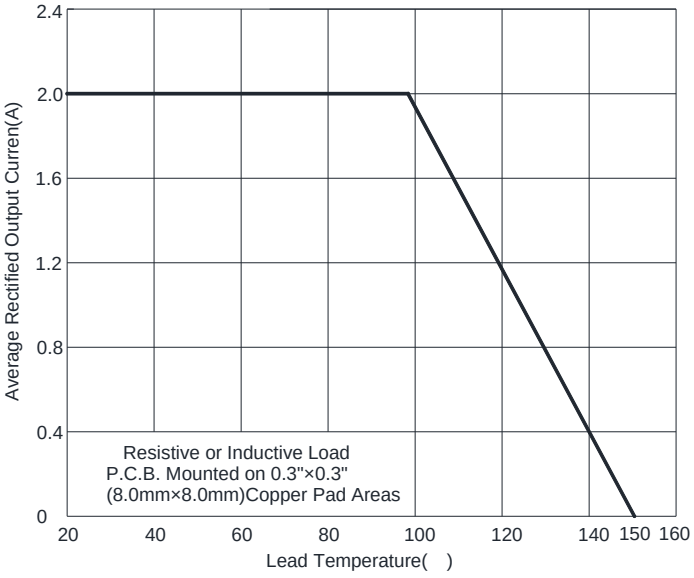
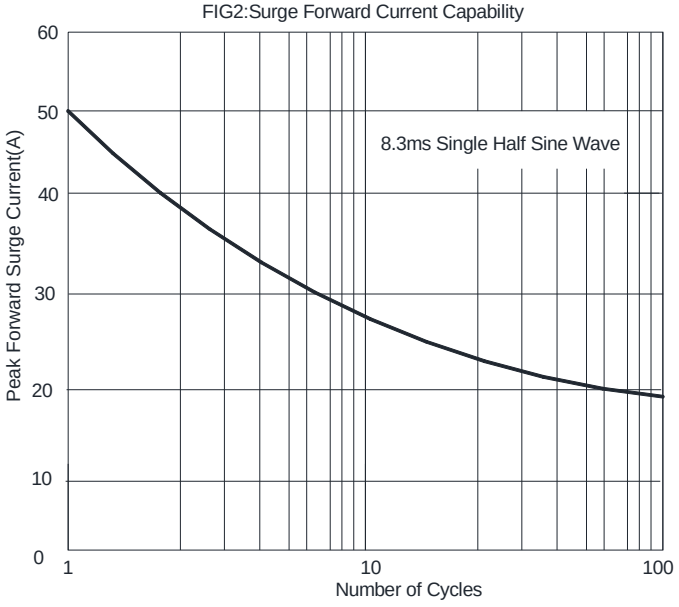
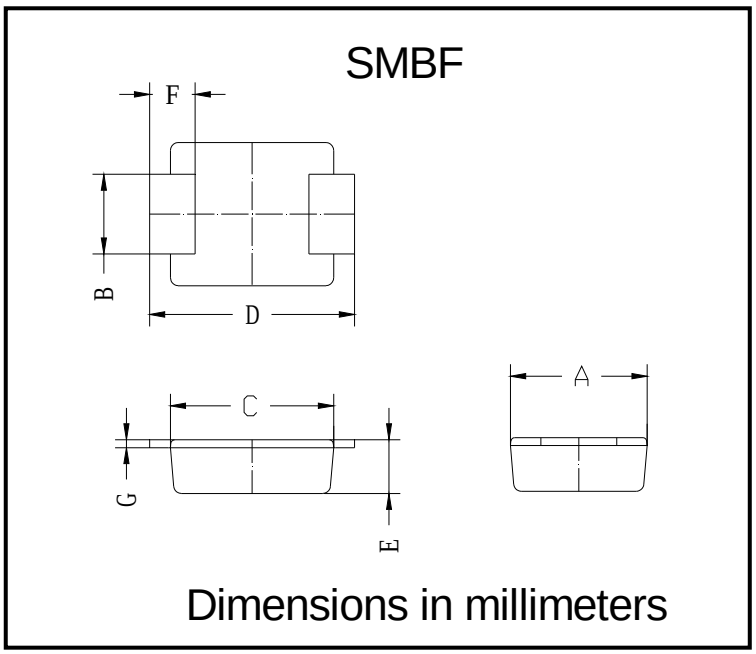


FIG2:Surge Forward Current Capability



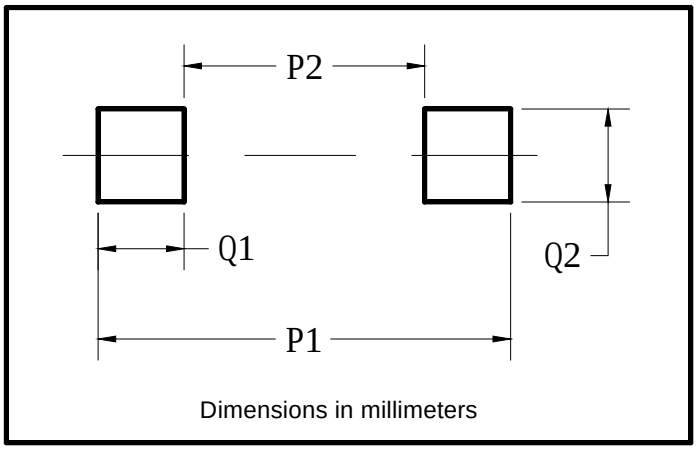
GR2ABF THRU GR2MBF

■ Outline Dimensions



SMBF		
Dim	Min	Max
A	3.40	3.80
B	1.90	2.10
C	4.15	4.45
D	5.10	5.60
E	1.05	1.55
F	0.70	1.35
G	0.15	0.25

■ Suggested pad layout



Dim	Milimeters
P1	6.20
P2	2.40
Q1	1.90
Q2	2.20

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